

March/April	May/June	July/August	September/October	November / December
Ad Closing 2019/02/20	2019/04/20	2019/06/20	2019/08/20	2019/10/20
Material Due 2019/02/25	2019/04/25	2019/06/25	2019/08/25	2019/10/25
Mailing Date 2019/03/01	2019/05/01	2019/07/01	2019/09/01	2019/11/01
Year Book 2019	Smart Manufacturing			
Industry Outlook 产业展望	Data Driven 数据融合与利用	Intelligent Robot 智能机器人	Human-Machine Collaboration 产线人机协作	Smart Factory 智慧工厂
Tech Investment	Compound Semiconductor			
SEMI Data 数据与投资项目汇总	GaN Devices GaN 器件	GaAs Devices GaAs 器件	SiC Devices SiC 器件	Compound Semiconductor Application 化合物半导体应用
Wafer Fabrication				
EDT 电子设计技术	Interconnects and Yield Improvement 互连和成品率提升	Wafer Cleaning Technology 晶圆清洗技术	IoT IC Process IoT IC 工艺	DFM&DFT 可制造设计 可测试设计
Packaging & Testing				
SEMICON China Preview	SiP Packaging 系统级封装	Wafer-Level Package 晶圆级封装	Micro Assembling 微组装	Test and measurement 测试与测量
e-Newsletter				
SEMI China Daily News	IC APP;	eCarChina;	Show Daily / WeChat during the SEMICON China	

AD.Type	Dimension width*height(mm)	File size	Format	1x(\$)	3x(\$)	5x(\$)
1	Full Page 200*267	>300dpi	JPEG / PDF / EPS	3,200	2,600	2,000
2	1/2 Page 200*134 (horz.,vert.,or island)	>300dpi	JPEG / PDF / EPS	1,920	1,560	1,200
3	Cover Two Spread 400*267 (inside front cover and page1)	>300dpi	JPEG / PDF / EPS	7,000	5,600	4,300
4	Cover Two 200*267 (inside front cover)	>300dpi	JPEG / PDF / EPS	4,000	3,200	2,400
5	Cover Three 200*267 (inside back cover)	>300dpi	JPEG / PDF / EPS	4,000	3,200	2,400
6	Cover Four 200*267 (back cover)	>300dpi	JPEG / PDF / EPS	4,900	4,000	3,000

* Please allow 3mm bleeds. Color model: CMYK